

Title (en)

EMISSION TIP ASSEMBLY AND METHOD FOR OPERATING SAME

Title (de)

EMISSIONSSPITZEN-ANORDNUNG UND VERFAHREN ZUR DEREN BETRIEB

Title (fr)

AGENCEMENT DE POINTES D'ÉMISSION ET SON PROCÉDÉ DE FONCTIONNEMENT

Publication

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Application

**EP 16701246 A 20160119**

Priority

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Abstract (en)

[origin: WO2016116269A1] The invention relates to an emission tip assembly (100) on high-voltage electrodes for charging or discharging substrates, comprising at least one emission tip (1) and a carrier body (7) composed of an insulating material, which has at least one high-resistance series resistor (13), wherein the at least one emission tip (1) can be connected to a high-voltage connection (14) by means of the series resistor (13). In order to have available an assembly of emission tips which, despite protrusion from the carrier body (7) thereof to any extent in principle and despite the metal profiled element (10, 10a) provided with the insulating potting mass (6), causes no injuries in the event of unintentional and intentional contact and thus permits safe handling together with high efficiency of the assembly, the emission tip (1) is formed of a spring metal and forms an elastic spring element, and a free end of the emission tip (1) is freely spaced apart from the carrier body (7), the particular metal profiled element (10, 10a), and the insulating potting mass (6), as a corona tip (2). In addition, the range effect of a discharge electrode is improved by the guiding of an auxiliary air quantity (15) directly to the corona tip (2).

IPC 8 full level

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